

MJD350

High Voltage Power Transistors D-PAK for Surface Mount Applications

- Lead Formed for Surface Mount Applications (No Suffix)
- Straight Lead (I-PAK, "- I" Suffix)



PNP Epitaxial Silicon Transistor

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------|----------------------------------------------------|------------|------------------|
| V_{CBO} | Collector-Base Voltage | - 300 | V |
| V_{CEO} | Collector-Emitter Voltage | - 300 | V |
| V_{EBO} | Emitter-Base Voltage | - 3 | V |
| I_C | Collector Current (DC) | - 0.5 | A |
| I_{CP} | Collector Current (Pulse) | - 0.75 | A |
| P_C | Collector Dissipation ($T_C = 25^\circ\text{C}$) | 15 | W |
| | Collector Dissipation ($T_a = 25^\circ\text{C}$) | 1.56 | W |
| T_J | Junction Temperature | 150 | $^\circ\text{C}$ |
| T_{STG} | Storage Temperature | - 65 ~ 150 | $^\circ\text{C}$ |

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Condition | Min. | Max. | Units |
|----------------|----------------------------------------|--------------------------------------------|------|------|-------|
| $V_{CEO(sus)}$ | * Collector-Emitter Sustaining Voltage | $I_C = 1\text{mA}, I_B = 0$ | -300 | | V |
| I_{CEO} | Collector Cut-off Current | $V_{CB} = -300\text{V}, I_E = 0$ | | -0.1 | mA |
| I_{EBO} | Emitter Cut-off Current | $V_{EB} = -3\text{V}, I_C = 0$ | | -0.1 | mA |
| h_{FE} | * DC Current Gain | $V_{CE} = -10\text{V}, I_C = -50\text{mA}$ | 30 | 240 | |

* Pulse Test: $PW \leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Characteristics

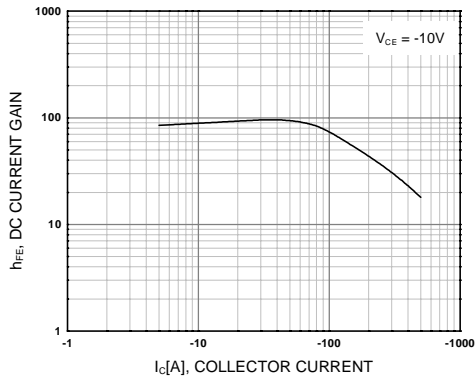


Figure 1. DC current Gain

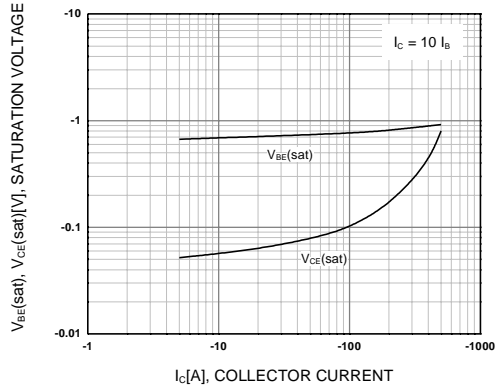


Figure 2. Base-Emitter Saturation Voltage
Collector-Emitter Saturation Voltage

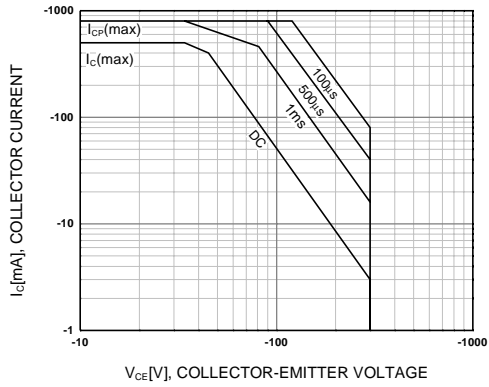


Figure 3. Safe Operating Area

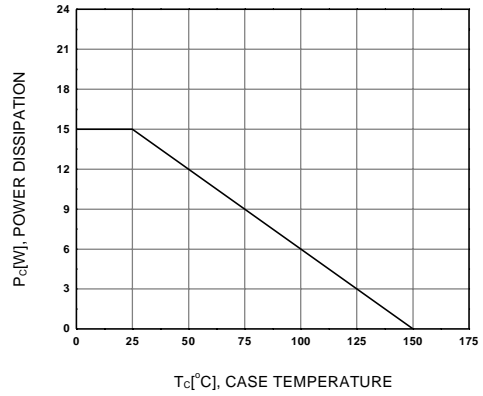


Figure 4. Power Derating

Package Dimensions

D-PAK



Dimensions in Millimeters

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